

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**  
*-- PATENT APPLICATION --*

Applicant: : Aron T. Lunde  
Application No.: : 10/053,963  
Filed: : January 22, 2002  
Title: : A DIE ASSEMBLY AND METHOD FOR FORMING A  
DIE ON A WAFER  
Examiner : Nguyen, Khiem D.  
Group Art Unit : 2823  
Confirmation No. : 5214  
Attorney Docket No. : 37829.0400

**RESPONSE TO OFFICE ACTION**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Applicant hereby responds to the Office Action dated August 16, 2006, and respectfully requests the Examiner to consider the following remarks. Because this paper is being submitted within the three month shortened statutory period, no fee is believed to be due. However, Applicant respectfully requests and authorizes that any fees due or any overpayments be charged or credited to Deposit Account No. 19-2814.

**Remarks/Arguments** begin on page 2 of this paper.

**Conclusion** begins on page 7 of this paper.